



2815
#

AMENDMENT TRANSMITTAL LETTER

Docket No.
YOR919990336US2

Application No.
10/054,605-Conf. #8304

Filing Date
November 13, 2001

Examiner
Paul E. Brock, II

Art Unit
2815

Applicant(s): Chao-Kun Hu

Invention: REDUCED ELECTROMIGRATION AND STRESS INDUCED MIGRATION OF COPPER WIRES BY SURFACE COATING

TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an amendment in the above-identified application.
The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	36	- 36 =		x	0.00
Independent Claims	2	- 3 =		x	0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify): Extension for response within second month					410.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					410.00

- ☒ Large Entity ☐ Small Entity
- ☐ No additional fee is required for this amendment.
- ☒ Please charge Deposit Account No. 50-0510 in the amount of \$ 410.00.
A duplicate copy of this sheet is enclosed.
- ☐ A check in the amount of \$ _____ to cover the filing fee is enclosed.
- ☐ Payment by credit card. Form PTO-2038 is attached.
- ☒ The Commissioner is hereby authorized to charge and credit Deposit Account No. 50-0510 as described below. A duplicate copy of this sheet is enclosed.
- ☒ Credit any overpayment.
- ☒ Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.

Burton A. Amernick
Attorney Reg. No.: 24,852

Dated: January 22, 2003

CONNOLLY BOVE LODGE & HUTZ, LLP
1990 M Street, N.W., Suite 800
Washington, DC 20036-3425
(202) 331-7111

RECEIVED
JAN 27 2003
TECHNOLOGY CENTER 2800



Docket No.: YOR919990336US2
(20140-00300-US)
(PATENT)

7/c
P. Walker
1-31-03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Chao-Kun Hu

Application No.: 10/054,605

Group Art Unit: 2815

Filed: November 13, 2001

Examiner: Brock II, Paul E.

For: REDUCED ELECTROMIGRATION AND
STRESS INDUCED MIGRATION OF COPPER
WIRES BY SURFACE COATING

AMENDMENT

Box Non-Fee Amendment
Commissioner for Patents
Washington, DC 20231

Dear Sir:

In response to the Office Action dated August 22, 2002 (Paper No. 5), please amend the above-identified U.S. Patent application as follows:

In the Claims

Please cancel claims 6 and 23 without prejudice to their reentry at some later date.

Please amend claims 1, 3, 5, 7-8, 18, 20, 22 and 24-25 as follows

1. (Amended) A method for forming conductors with high electromigration resistance comprising

- forming a layer of dielectric on a substrate,
- forming at least one trench in said layer of dielectric,
- forming a metal liner in said trench,
- forming a conductor on said metal liner filling said trench,

C1
cancel

RECEIVED
JAN 27 2003
TECHNOLOGY CENTER 2800